

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4225576	(die chip ic (integrated adj circuit) semiconductor flipchip (flip adj chip)) samd (bga bump ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 01:21
L2	409654	(substrate carrier board pcb ((wiring printed circuit) adj3 board)) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 01:22
L3	13020	(heat with (sink radiate spreader lid cover radiating radiated element)) same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 01:23
L4	3769	(package packaging packaged) same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 01:24
L5	1505	4 same (thermal thermally)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 01:24

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	123000	(die chip ic (integrated adj circuit) semiconductor FLIPCHIP (FLIP ADJ CHIP)) same (BGA BUMP BALL)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 00:44
L2	48565	(substrate carrier board pcb ((wiring printed circuit) adj3 board)) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 00:45
L3	161160	(heat with (sink radiate spreader lid cover radiating radiated element)) same "3"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 00:46
L4	2813	(heat with (sink radiate spreader lid cover radiating radiated element)) same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 00:46
L5	1525	(package packaging packaged) same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 00:47
L6	1153	5 and (thermal thermally)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 00:47